WWSWLT.040 20g

Datasheet revision 1.0 www.chipquik.com

Sn42/Bi57/Ag1 2.5% No-Clean Water-Washable Flux Core Solder Wire 1.0mm 20g

Product Highlights

LOW TEMPERATURE WITH FLUX CORE

Melts at 138°C (281°F)

No-Clean Water-Washable

2.5% flux core

Lead-Free

RoHS 3 and REACH compliant

Specifications

Alloy: Sn42/Bi57/Ag1 Wire diameter: 0.040" (1.0mm)

Flux Core: 2.5% No-Clean Water-Washable

Flux Classification: REL0

Melting Point: 138°C (281°F)
Packaging: 20g (0.7oz) Spool
Shelf Life: >60 months

Storage and Handling

Store in a non-corrosive, dry environment.

Please Note: Although Sn42/Bi57/Ag1 forms strong joints and is more ductile due to the added 1% Silver, in wire form it is brittle and needs to be handled gently when unspooling. It is normal for spooled Sn42/Bi57/Ag1 wire to have some breaks in it.

Test Results

| Test J-STD-004 or other requirements as stated | Test Requirement | Result |
|--|---|--|
| Copper Mirror | IPC-TM-650: 2.3.32 | L: No breakthrough |
| Corrosion | IPC-TM-650: 2.6.15 | L: No corrosion |
| Quantitative Halides | IPC-TM-650: 2.3.28.1 | L: <0.05% |
| Electrochemical Migration | IPC-TM-650: 2.6.14.1 | L: <1 decade drop (No-clean) |
| Surface Insulation Resistance 85°C, | IPC-TM-650: 2.6.3.7 | L: ≥100MΩ (No-clean) |
| 85% RH @ 168 Hours | | <u> </u> |
| Visual | IPC-TM-650: 3.4.2.5 | Clear and free from precipitation |
| Conflict Minerals Compliance | Electronic Industry Citizenship Coalition (EICC) | Compliant |
| REACH Compliance | Articles 33 and 67 of Regulation (EC) No 1907/2006 | Contains no substance >0.1% w/w that is listed as a SVHC or restricted for use in solder materials |

Conforms to the following Industry Standards:

| J-STD-004B, Amendment 1 (Solder Fluxes): | Yes |
|---|-----|
| J-STD-006C, Amendments 1 & 2 (Solder Alloys and Fluxed/Non-Fluxed Solders): | Yes |
| RoHS 3 Directive (EU) 2015/863: | Yes |

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